

- Accelerated testing, 378–382
failure mechanisms, 380
steps, 380
- Acceleration factor (AF), 360,
376–377, 378
- Accelerators, 66
- Acoustic impedance, 305–306
- Acoustic impedance polarity
detection (AIPD), 307, 307
- Acrylonitrile-butadiene rubbers, 75
- Addition, 48
- Addition cure, 95
- Additives, 47
- Adhesion strength
button shear test, 201
180°C peel test, 203
modified die shear test, 202
tab pull test, 202
- Adhesive, 6–8, 11, 30, 35, 75, 80, 91,
164, 254, 255, 267, 273, 275
- Adhesive strength, 254, 255
- Advisory Group on Reliability of
Electronic Equipment (AGREE),
352
- Aliphatic epoxies, 50
- Aliphatic tertiary amines, 65
- Alpha emission rates (AERs), 73, 74
- Alumina, 4, 68–69, 95
- Aluminum chelates, 73
- Aluminum nitride, 68, 88
- Amplifiers, 90, 440, 444
- Angular fillers, 70, 72
- Anhydrides, 51, 59–60
- Antimony pentoxide, 77
- Antimony trioxide (ATO), 76, 77,
102, 104, 108, 391
hazardous effects, 102–103
toxicity, 104
- Aperture-plate molds, 133, 134, 138
- Application requirements, 367
- Aromatic/aliphatic polyurethane,
53, 55
- Aromatic amines, 60, 61, 62, 65
- A-scan, 302, 304, 306
- ASTM C177 guarded hot-plate
method, 196
- ASTM D256A/D256B test, 199
- ASTM D638/D2990 test methods,
198
- ASTM D2240 durometer hardness
method, 188
- ASTM D2863 oxygen index test,
218, 219
- ASTM D696/SEMI G13-82, 190
- ASTM D3123/SEMI G11-88 test,
181
- ASTM D790-71 test, 200
- ASTM D1434 test, 212
- ASTM E595-93 test, 212
- Atmospheric-pressure plasma (APP),
173
- Atmospheric-pressure plasma jet
(APPJ), 173–174
- Atomic force microscopy (AFM),
288, 298, 342, 343
- Auger electron spectroscopy (AES),
335
- Auger pumps with RPDV, 150
- Autoclave test, 386–387
galvanic corrosion, 387
- Automated acid decapsulation,
293, 295
- Automotive electronics, 431, 432
- Bakelite, 54
- Baking, 260, 271
- Ball bond corrosion, 229
- Ball-grid array (BGA), 14, 98, 157

- Bathtub curve, 353
- Bentonite, 447–448.
 - See also* Montmorillonite
- Benzene ring, 50
- Biochip, packaged optoelectronic, 444
- Biocompatibility, 440, 445, 454
- Bio-devices
 - biocompatibility of, 440
 - electrode/amplifier assembly, 444
 - polymeric microfluidic devices, 445
- Bioelectronics, 440–445
- Bioelectronics, biosensors, and bio-MEMS
 - biosensor packaging process, 446
 - electrode and amplifier assembly, 444
 - packaged optoelectronic biochip, 444
 - polymeric microfluidic devices, 445
- Bio-MEMS, 440
- Biosensors
 - plastic encapsulation of ISFET, 446
- Biphenyl epoxy resins, 59
- Bisphenol A (bis A), 49
- Black's model, 369
- Bleed, 184
- Bond finger clearance, 240
- Bonding pads, 8, 11, 159, 170, 231, 235, 260, 273, 387–388
- Bond liftoff, 140, 227
- Bond-pad cratering, 227
- Bound water molecules, 206, 209
- Breakdown voltage, 216, 235
- Bright-field, 340–341
- Brittle fracture, 262–265, 262–265
 - measuring critical stress intensity factor, 264, 265
 - modeling Mode I crack, 263
- Brominated biphenyl oxide flame retardants
 - restricting use of, 105
- Brominated DGEBA, 76
- Brominated dioxins
 - toxic responses, 105
- Brominated flame retardants (BFR), 76, 102–107, 108.
 - See also* Halogenated flame retardants
 - hazardous effects, 102–103
 - timeline of actions, 106–107
 - toxicity, 104
- Bromine, 76, 87, 102, 107, 217
- B-scan, 302, 303, 309, 310, 317
- B-staged resin, 66
- Buckling, 229
- Bulk scan, 302, 307, 320
- Burn-in. *See* Stress screening
- Burrs on lead-frame, 262
- Button shear test, 201
- Calcium layer resistance measurement
 - method, 40
- Can and header, 3
- Carbon nanotube (CNT), 447
- Carboxylic, 59, 60
- Casting. *See* Potting
- Catalyst type, 61
- Cause and effect diagram.
 - See* Fish-bone diagram
- Cavity Direct Injection Molding (CDIM) technology (Apic Yamada Corp.), 429–430
 - advantages, 430
- Cavity printing, 36, 157, 159, 160, 168, 175
- Ceramic packages, 33–34
 - advantage, 34
 - application in MEMS, 33
- Chemical etching, 293, 297
- Chemical properties, 216, 216–218
- Chip crack, 201
- Chip-in-polymer (CIP), 24, 25, 162, 166
- Chip-level package, 20
- Chip-on-board, 89, 147–149

- Chip-on-flex (COF), 30
- Chip-on-flex MCMs (COF-MCMs), 30
- Chip scale packages (CSPs), 17, 18, 80, 157, 420
- Chip size, 240, 420
- C-mode, 302, 304, 305, 312–313, 315, 317, 319
- C-mode scanning acoustic microscope (C-SAM[®]), 302–303, 389
- Coefficient of hygroscopic expansion (CHE), 189, 208–210, 254
 - expansion of polymer chain, 211
 - measurement of hygroscopic swelling, 210
- Coefficient of moisture expansion (CME). *See* Coefficient of hygroscopic expansion
- Coefficient of thermal expansion (CTE), 2, 33, 34–35, 47, 69, 149, 159, 189–191, 208, 366, 431
- Cold shrinkage, 243, 244, 246
- Collectable volatile condensable materials (CVCM), 212
- Coloring agents, 78
- Combined load-stress condition, 276
- Commercial off-the-shelf (COTS), 1
- Compression molding technique, 145–146, 162, 164, 167, 425–427, 454. *See also* Flow Free Thin (FFT) molding system (Towa Corp)
- Compressive modulus, 62
- Compressive strength, 62
- Condensation, 49, 53
- Condensation cure, 92, 95–98
- Connectors, 2, 7, 36, 79, 90, 151, 175, 366, 420
- Contaminants, 1, 212, 273–274, 387
- Contamination level, 216–217
- Contributing factors, 235–236
- Conventional underfill, 155
- Corroded die, 227, 403
- Corrosion, 273, 273–274
- Corrosive gases, 31, 33, 39, 42, 211
- Coupling agents, 73
- Cracked lead, 227, 402
- Cracking potential, 197, 199
- Creep, 229, 235
- Critical failure mechanisms, 377
- Cross-bonded stacking, 23
- Cross-linking, 48, 189
- Cross-linking density, 193
- Crystal silica, 68, 69
- Cu bump bonding (CBB), 25, 26
- Cure cycle, 61, 100, 188–189
- Cure temperature, 182, 187
- Cure time, 189
- Curing agents/hardeners, 60–66
 - properties of DGEBA epoxy resin, 65
- Curing/hardening process, 48, 187–188
- Curing schedule, 91
- Cyanate ester, 11
- Cycled temperature, with constant humidity and bias, 388
- Cycloaliphatic amines, 65
- Cycloaliphatic epoxies, 51, 59
- Dam-and-fill technique, 147–149
- Dark-field, 299–300, 341
- De-adhesion. *See* Delamination
- Decabromodiphenyl ether (Deca-BDE), 104–107
- Decapsulation, 288, 290–296, 317, 347
 - comparison of methods, 291–292
 - decapsulator and decapsulated package, 295
 - mechanical, 296
 - plasma etching, 296
 - thermo-mechanical, 294, 296
- Defect and failure analysis techniques
 - atomic force microscopy, 342
 - destructive evaluation
 - analytical testing, 289–290
 - decapsulation (removal of encapsulant), 290–296
 - internal examination, 296
 - locating site and identifying mechanism, 297

- Defect and failure analysis techniques (*contd.*)
 - selective layer removal, 297
 - simulation testing, 297–298
- electrical testing, 288
- electron microscopy, 332–342
- infrared microscopy, 342–344
- non-destructive evaluation, 288–289
- optical microscopy, 298–301
- scanning acoustic microscopy, 301–321
 - case studies, 312–321
 - C-SAM®, 302–310
 - imaging modes, 302
 - scanning laser acoustic microscope, 310–312
- X-ray microscopy, 322–331
- Defects, 225, 227–228, 236, 287, 288, 313, 348, 399, 403–404
- Deflashing, 173–175
- Delaminated passivation, 227
- Delamination, 246–247, 246–247, 251–258, 251–258
 - crack propagation, 252
 - CTE mismatch strains and stresses, 247
 - effect of loads, 252–253
 - effect of package moisture absorption, 257
 - interface model, 255
 - mechanical model, 254
 - stages, 256
 - types, 246
- Depolymerization, 235, 235, 275, 275
- Desiccant, 211, 260, 449–450
- Design qualification.
 - See* Virtual qualification
- Destructive evaluation, 289, 289–298
- Destructive techniques, 288.
 - See also* Non-destructive techniques
- Die attach, 7, 11, 315–316, 429
- Die cracking, 245–246
- Dielectric constant, 37, 62–63, 214
- Dielectric strength, 216
- Die-paddle shift, 184, 289
- Die shear test, 201
- Die to wafer (D2W), 27
- Differential interference contrast, 300–301
- Differential scanning calorimeter (DSC), 186, 192, 290
- Diffusion coefficient, 203–204
- Diglycidyl ether of bisphenol A (DGEBA), 50, 50, 59
- Diisocyanate, 52–53
- Dimethyldichlorosilane (Di), 52
- Dissipation factor, 63, 214, 214
- 2D multi-chip module (2D MCM) packages, 18, 19
- Dow corning materials
 - silicone materials, 93
- 2D package, 12–19
- 3D package, 19–31
 - design, 23
 - encapsulation, 161–169
- 3D packaging process, 22
- 3D stacked die packages, 240
- 3D stacked molded interconnect device package, 29
- Dual-Core Intel Itanium 2 processor 9000 series, 417
- Dual in-line package (DIP), 13, 14, 134, 135, 276, 420
- Dual-stage sorption, 206
- Ductile fracture, 265–266
- Durometer, 93, 188, 290
- Durometer hardness test, 90, 290
- 3D wafer-level die stacking design, 25, 26
- 3D wafer-level package, 24–29
- 2D wafer-level package (WLP), 159–161
- Dye penetration test, 289
- Dynamic random access memory (DRAM), 420
- Economy of screening, 407–408
- EEC “glow wire” and “needle flame” tests, 391

- EIA/JEDEC, 355
- Ejection, 133, 135, 140–141, 188, 189
- Elastic deformation, 229
- Elastomers, 35
- Electrical open, 230–231, 232–233
- Electrical parameter drift, 230
- Electrical properties, 214–216
- Electrical resistance, 34, 40, 67, 115
- Electrical short, 257
- Electrical testing, 288
- Electronic packaging, 1, 7–10
 - high temperature electronics, 433
 - levels, 10
 - low temperature electronics, space applications, 433–434
 - silicon-germanium (SiGe) devices, 434
 - objectives, 7
 - operational temperatures for unheated spacecraft, 434
 - plastic package assembly flowchart, 8
 - tape-automated bonding (TAB) process, 9
- Electronics, 1
- Electron microscopy, 332–339
 - advantages, 333
 - electron–specimen interaction, 333–335
 - environmental scanning electron microscopy (ESEM), 337–339
 - scanning, 335–337
 - transmission electron microscopy, 339–342
- Electron-specimen interaction, 333–335
- Elongation, 198–200
- EME-U series, 115
- Encapsulant failures
 - brittle fracture, 262–265
 - delamination, 251–258
 - ductile fracture, 265–266
 - fatigue fracture, 266–268
 - vapor-induced cracking (popcorning), 258–262
- Encapsulant properties,
 - characterization of
 - chemical properties
 - flammability and oxygen index, 218
 - ion diffusion coefficient, 217
 - ionic impurity (contamination level), 216–217
 - electrical properties, 214–216
 - electrode arrangement, 215
 - hygro-thermomechanical properties
 - adhesion strength, 200–203
 - coefficient of hygroscopic expansion, 208–211
 - CTE and glass transition temperature, 189–195
 - flexural strength and modulus, 197–198
 - gas permeability, 211–212
 - moisture content and diffusion coefficient, 203–208
 - outgassing, 212–214
 - tensile strength, elastic, shear modulus and %elongation, 198–200
 - thermal conductivity, 195–197
- manufacturing properties
 - bleed and flash, 184
 - curing time and temperature, 187–188
 - gelation time, 183–184
 - hot hardness, 188–189
 - polymerization rate, 185–187
 - post-cure time and temperature, 189
 - rheological compatibility, 184–185
 - spiral flow length, 181–183
- Encapsulants
 - advantages, 34
 - dielectric strength, 216
 - market conditions and manufacturers, 79–80
 - other plastic encapsulation methods, 35–36

- Encapsulants (*contd.*)
 - plastic molding compounds, 34–35
 - properties, 182
- Encapsulated microelectronic packages
 - classification, 13
 - 2D packages
 - chip scale package, 18
 - dual in-line package, 14
 - flip-chip plastic ball-grid array package, 18
 - multi-chip module packages, 18–19
 - multi-chip-module plastic ball-grid array package, 19
 - pin-grid array package, 14
 - plastic-led chip carrier package, 16
 - quad flatpack, 16
 - single in-line package, 14
 - small-outline package, 15
 - substrate packages, 17–18
 - surface-mounted packages, 14–17
 - tape-automated bonding package, 17
 - through-hole mounted packages, 12–14
 - wire-bonded plastic ball-grid array package, 18
 - 3D packages
 - chip-in-polymer package, 25
 - 3D die stacking design, 26
 - folded packages, 31
 - homogeneous die stacking designs, 24
 - horizontally stacked die design, 20
 - and interconnection design, 22
 - interconnection metallization grooves, 23
 - interconnection vias in 3D WLP, 25
 - molded interconnect device package stacking design, 29
 - non-homogeneous die stacking designs, 24
 - SMAFTI technology, 28
 - stacked die, 20–29
 - stacked die package, 26
 - stacked package designs, 30
 - stacked packages, 29–30
 - stacked wafer packaging design, 29
 - through-silicon via process flow, 27
 - wire interconnection and die stacking design, 21
 - plastic package, 11
 - thermo-mechanical properties, 12
- Encapsulation defects
 - delamination, 246–247
 - die cracking, 245–246
 - flash, 250
 - foreign particles, 250
 - incomplete cure, 250
 - non-uniform encapsulation, 249–250
 - paddle shift, 241–242
 - voids, 247–249
 - warpage, 242–245
 - wire sweep, 236–241
- Encapsulation defects and failures
 - package defects and failures, 225–228
 - classification of failure mechanisms, 228–235
 - contributing factors, 235–236
- Encapsulation failures, 251
- Encapsulation of 3D packages
 - chip-level encapsulation and assembly of MID stacked packages, 170
 - compression molding, 167
 - die stack, 163
 - die stack with injection molding, 164
 - 3D interconnection via VPS, 169
 - 3D Thomson package, 165

- multi-chip module (MCM) stack package, 164
- process flow for chip-in-polymer package, 166
- stacked modular package, 168
- wafer-level stacked dies, 167
- Encapsulation of 2D WLP
 - compression molding, 162
 - process flow for Super CSP™, 163
 - WL-CSP, 161
- Encapsulation process technology
 - cleaning and surface preparation
 - deflashing, 173–175
 - plasma cleaning, 169–173
 - 3D packages, 161–169
 - 2D wafer-level packages, 159–161
 - glob-topping technology, 147–150
 - molding technology
 - comparison of molding processes, 146
 - compression molding, 145–146
 - injection molding, 143–144
 - reaction-injection molding, 144–145
 - transfer molding, 129–142
 - potting and casting technology
 - one-part encapsulants, 152–153
 - two-part encapsulants, 153–154
 - printing encapsulation technology, 157–159
 - types, 130
 - underfilling technology
 - conventional flow, 155–156
 - no-flow, 157
- Encapsulation techniques, 8, 90, 129, 157, 162, 168, 181, 248, 249, 423
- Energy dispersive X-ray (EDX) spectroscopy, 217
- Engineering thermoplastics (ETPs), 79
- Environmental loads, 363–364
- Environmentally friendly encapsulants, 1, 47, 102–121
 - toxic flame retardants, 102–107
- Environmental scanning electron microscopy (ESEM), 337–339
- Environmental stress, 275
- Epichlorohydrin, 49–51, 217
- Epoxies, 47, 49–51, 64
 - aliphatic, 50
 - cycloaliphatic, 51
 - Novolac, 51
- Epoxy cresol novolacs (ECN), 59
- Epoxy functionalities, 49
- Epoxy molded compounds
 - material development, 87
- Epoxy resins, 57, 59
 - mechanical and electrical properties, 61–63
- Error seeding, 402
- Ethylene-vinyl acetate (EVA), 452
 - copolymer encapsulants, 452–453
- Ethylene-vinyl acetate (EVA), 452
- Eutrophication, 116
- Failure accelerators, 268–276
 - combined load–stress conditions, 276
 - exposure to contaminants and solvents, 273–274
 - general environmental stress, 275
 - manufacturing and assembly loads, 276
 - moisture, 268–272
 - absorption and desorption, 270
 - residual stresses, 274–275
 - temperature, 272–273
- Failure analysis techniques,
 - selection of, 344–348
 - condition and construction of package, 345
 - defect and, 348
 - lateral resolution *versus* depth of penetration, 346
 - performance of analysis tool, 345
- Failure analysis techniques, selection of, 344–348

- Failure mechanism, 226, 228–235,
297, 355, 380
chemical loads, 235
classification, 234
electrical loads, 235
mechanical loads, 229
overstress failures, 229
PoF based models, 355
thermal loads, 229, 235
wearout failures, 229
- Failure mode, 230, 232, 370
- Failure modes, mechanisms, and
effects analysis (FMMEA),
369–371
flowchart, 370
severity ratings, 371
- Failure rate curve, 353–354
- Failure rates, 352
- Failures, 251–266
- Failure site, 226, 229, 230, 232, 297
- Fatigue crack, 229, 234, 266–268,
380
- Fatigue fracture, 266–268
mechanism, 266
- Feed-through interconnections (FTI),
26, 27
- Fickian moisture diffusion, 204, 205
- Filler content, 68, 69, 72
- Filler figure ratio, 72
- Fillers, 66–68, 66–73
advantages and disadvantages, 67
Alpha Emission Rate (AER), 74
effect of filler figure ratio, 72
effect of lowering CTE, 69
effect on thermal conductivity, 68
moisture ingress susceptibility, 72
particle size distribution, 71
typical and characteristic properties,
67
- Finite element analysis (FEA), 207
- Fish-bone diagrams, 236, 237
- Flame retardants, 76–77
properties of standard and
brominated epoxy resins, 76
resistance properties, 77
toxicity, 76
- Flammability, 218, 391
- Flammability and oxygen index, 218,
391
nonfeasibility. *See* EEC “glow
wire” and “needle flame” tests
- Flash, 9, 173, 184, 250
- Flexibilizers, 75
- Flexible OLEDs, 449
- Flexible solar cells, 453
- Flexural modulus, 197–198
- Flexural strength, 197–198
- Flexural strength and modulus
three-point bend test, 197
- Flip-chip plastic ball-grid array
(FC-PBGA), 17, 18
- Flow Free Thin (FFT) molding
system (Towa Corp). 427, 429
advantages, 427
- Flow resistance, 81
- Fluids dynamics analysis package
(FIDAP), 240
- Fluorescence microscopy, 301
- Fluorocarbons, 78
- Folded flexible circuit, 31
- Folded package, 31, 32
- Foreign inclusion, 228
- Foreign particles, 250
- Formaldehyde, 51, 54
- Fourier transform infrared (FTIR)
spectroscopy, 39
- Four-point loading test, 198
- Fowler–Nordheim model, 369
- Fractured die, 227, 245
- Fracture test, 200
- Free volume theory, 194, 195
- Functional diversification, 417–419
- Fused silica, 56, 66–71, 121
- Galvanic corrosion, 387
- Gang-pot molds. *See* Multi-plunger
molds
- Gas permeability, 211–212

- Gate position, 133, 238
- Gates, 133, 135, 238–239, 304, 307
- Gel time, 183–184
- General Electric materials
 - by-products of condensation cure RTV encapsulants, 98
 - condensation cure RTV encapsulants, 96, 97
 - material properties of addition cure RTV products, 98, 99
 - profile of RTV silicone, 95
 - RTV silicone application, 94
- GE-100 series, 116
- Glass Transition Temperature (T_g), 141–142, 189–195, 190, 191, 272
 - effect of cross-linking density, 193
- Glob top, 89–90, 147
- Glob-top encapsulants, 35–36, 89–90, 129, 147–150
 - Henkel Loctite Corporation, 91
- Glob-top technology
 - advantages and disadvantages, 147
 - Auger pumps with RPDV, 150
 - dam-and-fill encapsulation, 148, 149
 - encapsulant dispensing system, 148
 - encapsulated chip-on-board, 148
- Glop-top dispensing equipment, 147
- Green encapsulant material
 - development
 - flame resistance, 108
 - general approach, 109
 - green packaging, 108
 - with non-halogenated flame retardants, 111–116
 - advantages and disadvantages, 113–114
 - choices of non-toxic flame retardants, 111
 - comparison of mechanisms, 112
 - electrochemical reactions, 115
 - without flame retardants, 116–121
 - self-extinguishing mechanism, 117
 - Green encapsulants.
 - See* Environmentally friendly
- Green molding compounds
 - flame resistance, 121–122
 - lead-free solders, 253
 - Loctite, 118–119
 - Nitto Denko, 121
 - Shin-Etsu, 120
 - Sumitomo Bakelite, 117
- GR series, 116
- Guarded hot-plate method, 196
- Halogenated flame retardants, 102
- Halogens, 102
- Hardener. *See* Curing agent
- Hardness Shore D, 91, 188, 189
- Heat deflection temperature, 61
- Heat-sink small-outline package (HSOP), 15
- Hele-Shaw model, 248–249
- Helium leak test, 38–39
- Hermetic packages, 31–34, 36–42, 435
 - ceramic packages, 33–34
 - folded package designs, 32
 - metal flatpack, 32
 - metal packages, 33
 - properties of Kovar and Alloy 42, 33
- Hermetic testing, 39
- Hexabromocyclododecane (HBCD), 103, 104
- High density interconnection (HDI), 30
- Highly accelerated life test (HALT), 371, 372–373
 - strength limits and margins, 374
- Highly accelerated stress screening (HASS), 374
- Highly accelerated stress test (HAST), 110, 386, 396
- Highly accelerated temperature and humidity stress test, 388

- High-resolution scanning X-ray diffraction microscope (HR-SXDM), 328–329
 - advantage, 329
- High temperature
 - automotive electronics, 432
 - electronics, 431, 433, 448
 - hardness, 187, 188
 - maximum junction and operating ambient temperature extremes, 432
 - operation test, 384
 - storage test, 384
- Historical overview of encapsulation
 - “Can and header” transistor package, 3
 - Kovar transistor package, 2
 - pre-molded plastic package, 7
 - transfer molding, 4, 5
- History of qualification, 352–356
- Homogeneous stacking design, 23, 24, 240
- Hot chemical shrinkage, 243, 244
- Hot hardness. *See* High-temperature hardness
 - measurement from indentation resistance, 188
- Humidity tests
 - Autoclave test, 386–387
 - cycled temperature, with constant humidity and bias, 388
 - highly accelerated temperature and humidity stress test, 388
 - IPC/JEDEC J-STD-20 MSL classifications, 389
 - temperature-humidity-bias stress tests, 387
 - test to classify moisture sensitivity level for surface-mount devices, 388
- Humidity tests, 386–390
- Hydrated metal oxide powders, 78
- Hydrocarbon waxes, 78
- Hygroscopic mismatch strains, 209
- Hygroscopic swelling/expansion, 208
 - mechanism of, 209
- Hygro-thermomechanical properties, 189, 189, 220
- IEEE (Institute of Electrical and Electronics Engineers) 1413 standard, 355
- Imaging modes, 302
- Impact strength, 75
- Improper marking, 228
- Incomplete cure, 228, 250, 289
- Indentation resistance, 188
- Industry practices, 392–394
 - quality related terminology, 398
 - test conditions used in industry, 393
 - test methods and conditions, 395–397
- Industry practices, 392–394
- Inert flexibilizers, 74–75
- Inertial forces, 229
- Infant mortality failures, 353, 356, 375
- Infrared (IR) spectrographic analysis, 289, 290
- Infrared (IR) spectroscopy, 289
- Infrared microscopy, 289, 342–344
 - scanning infrared microscope, 344
- Inhibitor, 95
- Injection molding, 143–144, 146
 - apparatus, 143
 - disadvantage, 143
- In-mold cure time, 66, 84, 85
- Institute of Materials Research and Engineering (IMRE), 451
- Integrated circuit (IC) chips, 250, 417
 - chip-to-substrate and substrate-to-board packaging, 423, 426
 - miniaturization and integration trends, 419
 - packaging materials challenges, 428–429
 - pitch sizes, 423

- Intel's product qualification method, 355
- Internal examination, 296
- International Technology Roadmap for Semiconductors (ITRS), 420
 - challenges in future semiconductor packaging, 422–423
 - maximum junction and operating temperatures extremes of semiconductors, 432
 - semiconductor packaging and encapsulation, 421
- International Technology Roadmap for Semiconductors (ITRS), 420
- Ion diffusion, 268, 274
- Ion diffusion coefficient, 217
- Ionic impurity, 216–217
- Ionic purity, 88
- Ion-selective field effect transistor (ISFET), 445
- Ion-trapping agents, 78
- ISFET biosensors, 445
- Ishikawa diagram. *See* Fish-bone diagram
- ISO 9000, 409
- Isothermal fractional conversion, 186

- KMC-2000 Series, 116
- Known good die (KGD), 27
- Kovar package, 2, 33

- Lead corrosion, 9
- Lead-frame, 8–9, 11, 12, 37, 74, 121, 136, 227, 241, 255, 257–258, 261
- Lead-frame tab pull test, 201–202
- Lead-free solder, 86, 253
 - issues related to, 86
- Lead plating, 9, 173
- Lead trimming, 9, 110, 173
- LED
 - encapsulated with polymeric optical material, 451
 - inverted pyramid, 452
 - plastic encapsulation, 452
- Lewis acids, 59, 60, 65
- Life-cycle loads, 363–366, 371.
 - See also* Environmental loads;
 - Operational loads
 - in key applications, 365
 - load conditions imposed by manufacturing processes, 364
- Light-emitting diode (LED), 157, 175, 344
- Locating failure site, 297
- Low-pressure plasma (LPP), 173
- Low shrinkage, 59
- Low stress, 59, 371
- Low temperature
 - electronics, 431–434
 - operational temperatures, 434
- Low temperature co-fired ceramic (LTCC), 34

- Macro-voids, 206
- Manufacturers, parts family
 - assessment and qualification, 400–401
- Manufacturers of encapsulants, 79–80
- Marketing conditions of encapsulants, 79–80
- Mass production qualification, electronic packages, 351
- Materials development, 86–89
- Maximum pin count, 420, 424
- MCM-V (vertical multi-chip module), 22
- MCM with PBGA package design, 19
- Mechanical loads, 229
- MEMS packaging, 439–440, 441–442
- Metal hydrates, 77, 111–113
- Metal hydroxides, 77, 116
- Metallization corrosion, 35, 296, 388
- Metallization deformation, 201
- Metal package, 33
- Methyl, 52
- Micro-ball-grid array (μ BGA), 17

- Microelectromechanical systems (MEMS), 1, 33, 417, 435–440
- ITRS requirements and challenges, 442–443
- packaging options, 441
- plastic-encapsulated device, 438
- plastic-encapsulated pressure sensor, 438
 - plastic encapsulation process from Industrial Technology Research Institute, 437
 - pressure sensor from Motorola, 438
- plastic packaging process, 436
- plastic pre-molded package, 439
- requirements and challenges, 442–443
- Microelectronic device structure and packaging
 - CDIM process, 430
 - challenges in future semiconductor packaging, 422–423
 - chip-to-substrate and substrate-to-board bonding, 426
 - flow free thin molding technique, 429
 - miniaturization and integration trends, 419
 - Moore's law, "More than Moore" approaches, 418
 - number of transistors per chip, 418
 - packaging materials challenges, 428–429
 - single-chip package technology, 424, 425
 - stacked dies in wafer-level CSP, 427
- Microelectronic packaging
 - historical timeline and trend for, 421
- Micro-optoelectromechanical systems, 435
- Micro-voids, 206, 254
- MIL-HDBK-217 (military handbook), 352
- Miniaturization trend, 417, 419
- Minimum overall package profile, 424
- Misaligned leads, 226, 227, 403, 404
- Mix ratio, 93, 97, 99, 250
- MicroLeadFrame® (MLG®) package, 440
- Mode cracking, 22
- Moisture absorption, 270
- Moisture-barrier bag, 260
- Moisture concentration, 205, 208, 209, 211, 269, 271–272
- Moisture content, 203–208
- Moisture diffusion coefficient, 189, 203, 204, 205, 268, 272
- Moisture diffusion rate, 81
- Moisture sensitivity, 100
- Moisture Sensitivity Level (MSL), 110, 203, 388–390
- Moisture sensitivity levels
 - categories, 388–389
 - IPC/JEDEC standard classification, 389
- Moisture solubility coefficient, 205
- Moisture weight gain, 272
- Mold cavity thickness, 239
- Mold characteristics, 188, 189
- Mold-clamping pressure, 139
- Molded-interconnect device (MID), 29, 168, 170
- Molding compound preform (pellet), 129, 130, 132, 244
- Molding compounds, 11, 34, 47, 56–89, 108
 - accelerators, 66
 - coloring agents, 78
 - contents of epoxy, 57, 58
 - coupling agents, 73
 - curing agents or hardeners, 60–66
 - fillers, 66–73
 - flame retardants, 76–77
 - ion-trapping agents, 78
 - market conditions and manufacturers, 79–80
 - material properties, 81–85
 - key properties, 81
 - Nitto Denko, 82, 83, 121

- Plaskon, 82, 85
- Sumitomo Bakelite, 82, 84
- materials development, 86–89
- mold-release agents, 77–78
- properties, 82
- resins, 57–60
- status of epoxy manufacturers, 80
- stress-relief additives, 73–75
- transient thermal response, 88
- Molding pressure, 85, 240, 427, 454
- Molding processes
 - comparison of, 146
- Molding simulation, 141–142
- Mold-release agents, 77–78
- Montmorillonite, 447–448
- Moore's law, 417–418
- More than Moore, 417–419
- Mother board, 10
- Multi-chip modules (MCMs), 18–19, 157
- Multifunctional epoxy resin, 59
- Multi-plunger molds, 132–136
- Multi-scan, 302, 303
- Nano-material, disadvantage of, 449
- Nano-particles
 - nano-fillers, 447.
 - See also* Bentonite; Silica
 - particles, nano-sized; Zeolites
- Nano-sized particles, 448
- Nanotechnology, 445–449
 - and nanoelectronics
 - nano-fillers, 447
- Nitrogen-based substances, 77
- Nitto Denko, 80, 82
 - properties, 83
- No-flow underfill (NFU), 448–449
- Non-destructive evaluation (NDE), 288–289
- Non-destructive techniques, 287
- Non-Fickian Diffusion, 206–208
 - bound and unbound water
 - molecules, 206, 207
 - mechanisms of Fickian and, 208
- Non-halogenated
 - flame retardants, 111–116
 - inorganic flame retardants, 111
 - advantages and disadvantages, 113–114
- Non-hermetic package, 1, 439
- Non-homogeneity, 250
- Non-homogeneous stacking designs, 23, 24
- Non-uniform encapsulation, 249–250
- Novolac epoxies, 51, 57, 59, 88
- Octabromodiphenyl ether (Octa-BDE), 105
- OLED devices, 449–450
 - barrier coating, 450–451
 - packaging, 450
 - plastic encapsulant materials, 450
 - UV-cured epoxy resin, 449
- OLEDs, photovoltaics, and optoelectronics, 449–453
 - inverted pyramid, 452
- OLED packaging, 450
 - plastic encapsulation of LED arrays, 452
 - solar cell package, 453
- One-part potting encapsulants, 152–153
- Operational loads, 363
- Optical microscopy, 298–301
 - bright-field, 299, 300
 - dark-field, 299–300, 301
 - differential interference contrast, 300–301
 - fluorescence microscopy, 301
 - polarized light, 300
 - techniques, 299–301
 - Zeiss, 299
- Organic light-emitting diodes (OLEDs), 449–453
- Ortho-epoxy cresol novolac (O-ECN), 51
- Outgassing, 212–214
 - measurement, 213

- Overstress failures, 229
- Overstress screens, 401–402
- Oxygen index, 218, 391
- Package assembly, 8, 11, 242, 251, 273
- Package availability, 42
- Package cost, 37–38
- Package defects, 225–226
sites, types, and sources, 226–228
- Package designs, 420
- Package failures, 226–228
sites, modes, mechanisms, and environmental loads, 229, 230–233
- Package footprint, 19
- Package hermeticity, 38–40
- Package performance, 37
- Package reliability, 59, 110, 129
- Package weight, 36–37
- Packaging levels, 10
- Packaging materials challenges, 428–429
- Packing, 139
- Packing pressure, 139
- Paddle-shift, 241–242
- Partition-cell method, 211
- Passivation layer crack, 75
- Passivation pin holes, 227
- PCBs. *See* Printed circuit boards (PCBs)
- Pecht and Rudra model, 369
- Peel strength, 75
- Peel test, 202–203
- PEMs. *See* Plastic-encapsulated microelectronics (PEMs)
- Pentabromodiphenyl (Penta-BDE), 104, 105
- Percentage (%) elongation, 198–200
- Permeation curve, 212
- Phenol, 51, 60, 66
- Phenol-formaldehyde, 51, 54
- Phenolic and cresol novolacs, 59
- Phenolic resins, 54–56.
See also Bakelite
- Phenolics, 54–56, 64
- Phenyl, 52
- Phosphorous-based flame retardants, 115–116
- Phosphorus-containing retardants, 77
- Photovoltaic solar cells, 451
- Physics-based modeling, 236
- Physics-of-failure (PoF) approach, 351, 354, 358
physical properties as inputs, 366
reliability prediction using, 367–369
- Pin-grid array (PGA), 6, 13, 14, 15
- Pin-holes on lead coating, 226, 227
- ½ pitch size trend, 424
- Plaskon, 80, 82
- Plasma cleaning, 169–173, 175
APPJ apparatus, 174
comparisons of studies, 172
low-pressure plasma (LPP)
cleaning, 173
YES G1000 plasma cleaner, 171
- Plasma-enhanced chemical vapor deposition (PECVD), 7, 450–451
- Plasma etching, 164, 290, 292, 296
- Plastic ball-grid array (PBGA), 17, 171, 242, 294
- Plastic deformation, 229
- Plastic dual in-line packages (PDIPs) 13
- Plastic encapsulant materials
chemistry
addition polymerization process, 48
advantages and disadvantages of polymeric materials, 64
benzene ring, 50
condensation or step-growth polymerization, 49
DGEBA monomer and higher molecular weight polymer, 50
epoxies, 49–51
epoxy functionality, 49
epoxy novolac formation, 51

- ortho-epoxy cresol novolac, 51
- phenolics, 54–56
- polymers chains, 48
- polyurethanes, 52–54
- silicones, 52
- environmentally friendly or “green” encapsulants
 - material development, 107–121
 - toxic flame retardants, 102–107
- glob-top encapsulants, 89–90
- potting and casting encapsulants
 - dow corning materials, 90–91
 - general electric materials, 91–95
 - underfill encapsulants, 95–101
- Plastic-encapsulated microelectronics (PEMs), 39, 59, 132
- Plastic-leaded chip carrier (PLCC), 14, 16, 172, 294
- Plastic package
 - pre-molded/post-molded, 6–7
- Plastic pin-grid array package, 14, 15
- Plastic *versus* hermetic packages
 - availability, 42
 - cost, 37–38
 - hermeticity, 38–40
 - conditions for helium fine leak testing, 39
 - evaluation of cavity package, 39
 - performance, 37
 - reliability, 40–42
 - thermo-mechanical, 41
 - size and weight, 36–37
- Polarized light, 300
- Polybrominated biphenyls (PBBs), 103
- Polybrominated dibenzodioxins (PBDDs), 105
- Polybrominated dibenzofurans (PBDFs), 105
- Polybrominated diphenyl ethers (PBDEs), 103–104
 - ban of, 105
- Polybutylacrylate (PBA), 75
- Polydimethylsiloxane (PDMS), 52, 52, 53, 445
 - formation, 53
- Polyimide, 7, 11, 17, 35, 79, 203, 210, 261, 296, 325
- Polymerization rate, 185–187
 - conversion *versus* time, 187
- Polymerization reactions, 48
 - addition process, 48
 - condensation process (step-growth mechanism), 49
- Polymers, 48
- Polymethyl methacrylate (PMMA), 75
- Polyolefinic compounds, 50
- Polyurethanes, 52–54
 - aromatic/aliphatic, 55
 - classifications, 53–54, 55
 - unblocking mechanism, 56
- Poor solder wetting of lead, 227
- Popcorning, 258–262
- Popcorn resistance, 59–60
- Porosity, 185, 319–320
- Post-cure temperature, 189
- Post-mold cure time, 57, 110, 141, 193, 229, 243
- Post-molded package, 6
- Potential failure mechanisms, 371
- Pot life, 91
- Potting, 3, 36, 90–95, 151–154
- Potting and casting encapsulants, 36, 90–95
 - with silicone material, 92
- Potting and casting technology, 151–154
 - guidelines, 153
 - insulcast[®] epoxy compound, 151
 - one-part encapsulants, 152–153
 - two-part encapsulants, 153–154
 - advantages, 154
- Potting geometry, 152
- Power and temperature cycling, 385–386
- Power supplies, 90, 151
- Pressure cooker test. *See* Autoclave test

- Printed circuit board (PCB), 7, 79, 147, 242, 251, 258, 368, 371, 420, 440
- Printing encapsulants, 101–102
- Printing encapsulation, 157–159
 - materials, 101–102
 - method, 36
- Printing encapsulation technology
 - encapsulated WL-CSP, 160
 - planarization process, 158
 - process flow, 158, 159
 - stencil, 157–158
- Processing residuals, 212
- Product characteristics, 366–367
 - manufacturing processes, material properties, 366
- Product development process flow, virtual and product qualification, 359
- Product qualification, 351, 358, 371–372
 - accelerated testing, 378–382
 - failure mechanisms, 380
 - flowchart, 372
 - HALT process, 373
 - levels of, 375
 - accelerated testing and TTF measurement, 376–377
 - comparison, 376
 - goal certification, 376
 - similarity, 375–376
 - modeling and validation, 378
 - operating and destruct limits, 375
 - qualification levels, 375
 - qualification requirements, 374–377
 - qualification test planning, 377–378
 - reliability assessment, 382–382
 - strength limits and highly accelerated life test, 372–374
 - strength limits and margins, 374
 - TTF of product life using PoF models, 379
- Q factor measurement method, 40
- Quad flatpack (QFP), 14, 16, 37, 59, 134, 137, 185, 241, 259, 294, 423
- Qualification, 351
- Qualification accelerated tests
 - flammability and oxygen index test, 391
 - humidity tests, 386–390
 - radiation hardness, 392
 - salt atmosphere test, 391
 - solderability, 391–392
 - solvent resistance test, 390
 - steady-state temperature test, 384
 - thermal cycling test, 385–386
- Qualification and quality assurance
 - industry practices, 393–394
 - example test conditions, 393
 - test methods and conditions, 395–397
 - product qualification
 - accelerated testing, 378–382
 - modeling and validation, 378
 - qualification requirements, 374–377
 - qualification test planning, 377–378
 - reliability assessment, 382–383
 - strength limits and highly accelerated life test, 372–374
- qualification accelerated tests
 - flammability and oxygen index test, 391
 - humidity tests, 386–390
 - radiation hardness, 392
 - salt atmosphere test, 391
 - solderability, 391–392
 - solvent resistance test, 390
 - steady-state temperature test, 384
 - thermal cycling test, 385–386
- qualification and reliability assessment, 352–356
- qualification process overview, 356–361

- virtual qualification
 - application requirements, 367
 - failure modes, mechanisms, and effects analysis (FMMEA), 369–371
 - life-cycle loads, 363–366
 - product characteristics, 366–367
 - reliability prediction using PoF approach, 367–369
- Qualification process, 351, 356.
 - See also* Life-cycle loads
 - elements of, 359–360
 - objectives of, 360–361
 - qualification and quality assurance test, 360
 - and reliability assessment
 - bathub curve, 353
 - history, 352–356
 - reliability prediction
 - methodologies, 357
 - rollercoaster curve, 354
 - stages, 358
 - stages, 358
 - virtual and product qualification, 359
- Qualification requirements, 374–377
- Qualification test planning, 377–378
- Qualitative accelerated testing, product, 379, 383–384
- Quality, 351
- Quality, International Standards Organization (ISO), 394
 - quality assurance, 398–399
 - quality conformance, 394–398
- Quality assurance
 - failure distribution pattern, 406, 407
 - quality related terminology, 398
 - screening, 399–400
 - screens and defects, 403–404
 - screen selection
 - economy of screening, 407–408
 - root-cause analysis, 406–407
 - screen duration, 405–406
 - screen stress levels, 402–405
 - statistical process control, 408–410
 - Six Sigma process DMAIC, 410
 - Six Sigma statistical goal, 409
 - stress screening and burn-in, 400–401
 - TTF distribution characteristic, 406
- Quality assurance testing/screening, 358
- Quantitative accelerated testing, product, 379
- Quantitative B-scan analysis mode (Q-BAM™), 302, 309, 310
- RADC Reliability Notebook in 1959, Reliability Applications and Analysis Guide, 352
- Radiation, 73
- Radiation hardness, 392, 394
- Radioisotope heating units (RHUs), 433
- Ragged fillers, 70
- Ram-follower device, 182
- Random failure rate, 353
- Reaction-injection molding, 144–145
 - advantage, 144
- Reactive flexibilizers, 74
- Red phosphorus flame retardants, 111, 115
- Reflection-mode techniques, 308–309
- Relative permittivity, 214
- Reliability assessment, 352–356, 382–383
- Reliability Factors for Ground Electronics Equipment, 352
- Reliability modeling, 353
- Reliability prediction
 - methodologies, comparison, 356
 - using PoF approach, 367–369
- Reliability Stress Analysis for Electronic Equipment, 352
- Requirement trends, 420
- Residual stresses, 274–275

- Resin bleed, 173, 184
- Resin-filler interface, 206, 208
- Resins, 57–60
- Resin transfer molding, 144
- Restriction of the use of certain
 - Hazardous Substances (RoHS), 105
- Rheological compatibility, 184–185
 - effect of moisture, 186
- Rollercoaster curve, 354
- Room Temperature Vulcanization (RTV), 91, 95, 152
- Root-cause analysis, 406–407
- Rotary positive displacement valve (RPDV), 149, 150
- RTV silicones, 92
- Salt atmosphere test, 391
- Sample size selection, 377–378
- SCAN[®] filler, 88
- Scanning acoustic microscopy (SAM), 248, 287, 301, 330, 332.
 - See also* Acoustic micro-imaging (AMI)
 - case studies, 312–321
 - C-SAM[®], 302–310
 - acoustic impedance values, 306
 - acoustic scan, 305
 - acoustic wave reflectivity, 306
 - A-scan imaging, 304
 - B-scan, 310
 - crack profile, 309
 - die surface, 305
 - quantitative B-scan analysis, 310
 - versus* SLAM[™], 308
 - through-transmission scan, 307
 - time-of-flight scan, 308
 - imaging modes
 - acoustic, 303
 - scanning laser acoustic microscope
 - acoustic fringes, 312
- Scanning and transmission electron microscopy (STEM), 333
- Scanning electron microscopy (SEM), 288, 329, 333, 335–337
- Scanning laser acoustic microscope (SLAM[™]), 302, 310–312
 - acoustic fringes, 312
 - operating principle, 311
- Screen duration, 405–407
- Screening, 399–400
 - economy of, 407–408
- Screen printing, 157
- Screens, 402
 - defects they expose, 403–404
 - duration, 405–406
 - failure density, 405
 - failure distribution pattern, 406, 407
 - TTF distribution characteristic, 406
- Screen selection, 401–402
 - duration, 405–406
 - root-cause analysis, 406–407
 - stress levels, 402–405
- Selective layer removal, 297
- Self-extinguishing green molding
 - compound, 121
- SEMATECH, 355
- Semiconductor technology
 - chip size, 420
 - packaging
 - challenges in, 421
 - emerging technologies, 434–435
 - and encapsulation technology trend, 421
 - glass transition temperature, 433
 - used in automotive applications, 433
 - physical limits, 417
 - temperature requirements, 432–433
- SEMI G29 procedure, 216
- SEMI G45-88 test, 184
- Shadow-Moiré method, 289
- Shear rate, 140, 182, 185, 200
- Shear thinning behavior, 185–186

- Shrink small-outline package (SSOP), 15
- Signal propagation speed, 37
- Silanes, 73
- Silica-coated alumina nitride (SCAN), 68, 88
- Silica particles, nano-sized, 448
- Silicone elastomers, 75
- Silicon efficiency, 19
- Silicones, 52
 - condensation mechanism, 53
 - formation of polydimethylsiloxane (PDMS), 53
 - free-radical addition polymerization, 54
 - general formula, 52
 - polydimethylsiloxanes, 52
- Siloxane polymer, 52
- Simulation testing, 297–298
- Single-chip packages, 29, 30
 - performance and thermal characteristics, 420
 - trends based on ITRS, 424
- Single-chip WLPs, 159–160
- Single in-line package (SIP), 13, 14
- Six sigma process, 409–410
- SMAFTI assembly process, 27, 28
- SMAFTI (SMArt chip-FTI) technology, 26, 27, 165
- Small-outline integrated circuit (SOIC) package, 435
- Small-outline J-leaded (SOJ), 15
- Small-outline package (SOP), 14, 15, 147, 420
- “S-N curve,” fatigue failure curve, 352
- Solar cell modules, 451–452, 453
 - flexible, 453
- Solderability, 391–392
- Solvent resistance test, 390
 - encapsulant chemical resistance test, 390
- Spherical fillers, 70
- Spiral flow test, 181
 - molding tool, 183
- Stacked die packages
 - 3D chip-level packages, 20–24
 - 3D wafer-level-packages, 24–29
- Stacked package, 29–30
- Stacked QFP-format MCM, 30
- Statistical process control, 408–410
 - Six Sigma process DMAIC, 410
 - Six Sigma statistical goal, 409
- Statistical process control, 408–410
- Steady-state temperature test, 384
 - high-temperature operation test, 384
 - high-temperature storage test, 384
- Stencil printing, 36, 157, 158
- Step-stress analysis, 402
- Storage floor life, 261
- Strain energy release, 252–253, 267
- Strain range based model, 369
- Strength limits, 372–374
- Stress intensity factor, 252, 259, 263–267
- Stress-relief additives, 73–75
 - influence of flexibilizers on epoxy resins, 75
- Stress screening, 400–401
- Stress screens, 401
- Substrate, 17–18
- Sumikon[®] EME, 116
- Sumitomo Bakelite, 80, 82
 - properties, 84
- Super-resolution X-ray microscope (SR-XM), 329
- Surface cleanliness, 257
- Surface-mount technology, 14–17
- Surface scan, 302, 303
- Swelling, 208
 - measurements, 210
- Syringe valve, 149–150
- System-in-package (SiP), 248, 419
- System integration, 419, 420
- System-on-chip, 419
- System-on-package (SoP), 420

- TAB package, 17
- Tack-free time, 92
- Tape-automated-bonded plastic ball-grid array (TBGA), 17
- Tape-automated bonding (TAB), 9, 17, 89
- Telescopic design, 24
- Temperature cycling, 385
- Temperature-humidity-bias stress tests, 387
- Tensile modulus, 61, 198
- Tensile strength, 198–200
- Tetrabromobisphenol A (TBBPA), 103
- THB tests, 277
- Thermal conductivity, 195–197
 - guarded hot-plate technique, 196
- Thermal cycling test
 - power and temperature cycling, 385–386
 - temperature cycling, 385
 - thermal shock, 385
- Thermal loads, 229
- Thermal mismatch stress, 47, 70, 251
- Thermal shock, 385
- Thermal stability, 34–35, 60
- Thermal strain, 247, 273
- Thermomechanical analyzer (TMA), 191–192, 209
- Thermo-mechanical properties, 12
- Thermoplastic polymers, 79, 452
- Thermoplastics, 34–35
- Thermosets, 129
- Thermosetting polymers, 4, 34–35, 48
- Thin small-outline package (TSOP), 1, 16, 249
- Thomson approach, 22, 162
- Three-point bend test, 197
- Through-hole technology, 12
- Through-silicon via (TSV), 26, 27
- Through-transmission.
 - See* THRU-Scan™
- Through-vias (TV), 24–26, 168
- THRU-Scan™, 302, 307–308, 313, 316
- Time-of-flight (TOF), 302, 308, 319
- Times-to-failure (TTF), 361, 368, 379, 382, 383, 406
- Tin–lead (Sn–Pb) eutectic solders
 - abolishing use of, 86
- Tin whiskers, 229
- Titanates, 73
- TMA. *See* Thermo-mechanical analyzer
- Toluene (toluene) diisocyanate (TDI)
- Total mass loss (TML), 212
- Towa Corp. *See* Flow Free Thin (FFT) molding system (Towa Corp)
- Towers of Hanoi design, 23, 24, 240
- Toxic flame retardants
 - chemical structure of PBDE, PBB, TBBPA, and hexabromocyclododecane, 103
 - timeline of actions taken on BFRs, 106–107
 - toxicity of BFRs and antimony trioxide, 104
- Transfer molding, 129
 - aperture-plate mold, 134
 - cavity filling, 139
 - comparison of tools, 133
 - defined, 129
 - designs, 132
 - different parts, 137
 - encapsulation of quad flatpacks, 137
 - equipment, 131–136
 - glass transition temperature, 142
 - limitations, 130–131
 - multi-plunger mold, 134, 135, 136
 - simulation, 141–142
- Transfer molding process, 129, 131, 136–141
 - process flow, 138
 - stages, 138
 - transfer rate control, 141

- Transfer plunger, 129, 132, 134, 136–140
- Transfer-plunger pressure (transfer pressure), 139–140
- Transfer pot, 129, 130, 132
- Transfer-rate control, 141
- Transformers, 7, 36, 90, 191, 235
- Transmission electron microscopy (TEM), 333, 339–342
 - bright-field mode, 340–341
 - dark-field mode, 341
 - diffraction contrast, 341
 - high-resolution mode, 341–342
- Trapped gas, 212
- Tray-scan, 302, 303, 320
- Trends and challenges
 - emerging technologies
 - bioelectronics, biosensors, and bio-MEMS, 440–445
 - microelectromechanical systems, 435–440
 - nanotechnology and nanoelectronics, 445–449
 - OLEDs, photovoltaics, and optoelectronics, 449–453
 - extreme high- and low-temperature electronics, 431–434
 - microelectronic device structure and packaging, 417–431
- Trial-and-error methods, 235, 236
- Trifluoropropyl, 52
- True positive displacement pump (TPDP), 150
- Tungsten plug, 27, 29
- Two-part potting encapsulants, 153–154
- UL flame class, 81
- UL vertical flammability test, 218, 219
- Unbalanced encapsulant flow, 241
- Unbound water molecules, 206
- Underfill, 98
- Underfill encapsulants, 36, 95–101
 - advantages, 98, 100
 - Henkel Loctite Corporation, 101
 - key properties, 100
 - recent advances, 100
- Underfilling technology, 154–157
 - advantages and disadvantages, 154
 - conventional flow, 155–156
 - conventional *versus* no-flow process flow, 155
 - factors related to void-free, 156
 - flip-chip encapsulation, 156
 - no-flow
 - disadvantages, 157
- Underwriters Laboratory (UL), 76, 218, 391
- Vacuum printing encapsulation system (VPES), 158–159, 247, 248
- Vapor-induced cracking, 258–262.
 - See also* Popcorning
 - contributing factors, 260
 - preventing package cracking, 260–262
 - quad flatpack cracking, 259
 - stages, 258
- Vapor-induced delamination, 251–252, 258, 261, 275
- Vertical flammability test, 218
- Vertical multi-chip module (MCM-V), 22
- Via first method, 25
- Via last method, 25
- Vibration, 229, 345, 363–364, 368–369
- Vicker hardness, 67
- Vinyl, 52
- Virtual qualification, 351, 361–370
 - flowchart, 362
 - life-cycle loads, 365
- Viscosity, 185, 200–201
- Visual examination, 288
- 3V™, 302, 303
- Voids, 247–249
 - air-trap formation, 249

- Voids (*contd.*)
 defect and void-free encapsulation, 248
 Hele-Shaw model, 248–249
- Volume resistivity, 215, 216
- Wafer-level chip-scale package (CSP), 427
- Wafer-level package (WLP), 1, 20, 24–29, 145, 157, 159–161, 420, 427, 440, 454
- Wafer-level packaging, 440
- Wafer-level underfill (WLU), 449
 advantages of, 449
- Wafer to wafer (W2W), 27
- Warpage, 242–245
 concave mode, 243
 contributing factors, 243–245
 effect of encapsulation
 composition, 245
 modes, 242
 temperature profile, 243
 volume shrinkage, 244
- Waste from Electrical and Electronic Equipment (WEEE), 105
- Water vapor regained (WVR), 212
- Wearout failures, 229, 274, 353, 356, 381, 402, 405
- Wearout screens, 401
- Weighed-cell method, 211
- Wet chemical decapsulation
 technique, 290
- Wetting balance test, 392
- Wire ball bond fracture, 226, 229
- Wire-bonded plastic ball-grid array (PBGA), 17, 18
- Wire bond height, 240
- Wire diameter, 238, 239
- Wire orientation angle, 239
- Wire sweep, 236–241
 contributing factors, 238
 density, 238–240
 diameter and breaking load, 239
 extent, 239
 geometrical parameters, 240
 profiles, 241
- Working time. *See* Pot life
- X-ray contact microscope, 325–327
 parameters and aspects, 326
- X-ray fluorescence spectroscopy, 331–332
 operating modes, 331–332
- X-ray generation, 322–325
- X-ray microscopy
 advantages, 321–322
 case study: encapsulation in
 plastic-encapsulated devices, 329–331
 contact microscope, 325–327
 generation and absorption, 322–325
 absorption coefficient *versus* X-ray
 wavelength, 325
 X-ray tube, 323
 X-ray wavelengths, 324
 high-resolution scanning
 diffraction microscope, 328–329
 projection microscope, 327–328
 principle, 328
- X-ray projection microscope, 327–328
- X-ray wavelengths, 324, 325
- Zeolites, 448
- Zirconaluminates, 73